



Electronic Technical Data Sheet BALVER ZINN SOLDER PASTE PF32G SFMQ SN96C (SnAg3.8Cu0.7)

General information

BALVER ZINN SOLDER PASTE PF32G SFMQ SN96C is a lead-free,* No-Clean, solder paste for air or nitrogen reflow applications. The unique flux composition of **BALVER ZINN SOLDER PASTE PF32G SFMQ SN96C** provides excellent print and reflow characteristics with lead-free alloys. Print speeds can be achieved up to 150mm/s with excellent characteristics down to 16 – 20 mils pitch. The post soldering residues of **BALVER ZINN SOLDER PASTE PF32G SFMQ SN96C** are very low and concentrated around the pad. **BALVER ZINN SOLDER PASTE PF32G SFMQ SN96C** is a no clean formulation. The residues can remain on the board after reflow and will not interfere with in-circuit test. The residues are not harmful. The paste flux system of **BALVER ZINN SOLDER PASTE PF32G SFMQ SN96C** shows long tack life until 24 hours and long stencil life until 8 hours. The paste flux compositions allows reflow profiles with a peak temperature of 235°C – 250°C and enable a wide process window with lead-free solders. **BALVER ZINN SOLDER PASTE PF32G SFMQ SN96C** is also suitable for vapour phase soldering at temperatures over 230°C. **BALVER ZINN SOLDER PASTE PF- 32G SFMQ SN96C** is available as a licensed lead free alloy. SN96C-SnAg3,8Cu0,7 (JPN 3027441; US 5527628).

***BALVER ZINN SOLDER PASTE PF32 SFMQ SN96C** does not contain hazardous substances beyond the limits prescribed by EU Directive 2011/65/EU ("RoHS II").

Technical information and further Technical Data Sheets can be found on our website (www.BALVERZINN.com). You can also obtain all information and documents directly from **BALVER ZINN**.

BALVER ZINN Production Programme

The **BALVER ZINN** production programme also includes solder pastes, flux and solder wires. Beside the **SN100C®** product family, **BALVER ZINN** offers additional unpatented and patented solder alloys for wave soldering, reflow and rework.

Product Properties

- Flux classified according to J-STD-004 as: **ROLO**
- Paste classified according to EN 61190-1-2: **ROLO**
- Alloy classified according to **J-STD-006B**
- Solder paste according to **J-STD-005**
- RoHS compliant*
- Compatible with RoHS conform solder masks
- Long tack time of up to 24 hours
- Excellent print results with 16 and 20 mils pitch

Physical and Chemical Properties of flux PF32G SFMQ

Metal content:	86 – 89%
Viscosity: Malcom viscometer @ 10 rpm and 25°C	185Pas
Initial Tackiness: J-STD-004, IPC-TM-650, Method 2.4.44	138gf
Slump Test: JIS-Z-3284 Appendix 7; Appendix 8	pass
Solder Ball Test: JIS-Z-3284 Appendix 11	pass
Wetting Test: JIS-Z-3284 Appendix 10	pass
Copper Plate Corrosion: JIS-Z-3197 6.6.1	pass
SIR, IPC: J-STD-004, IPC-TM-650, Method 2.6.3.3	pass

Standard application:

88,5 – 89% Metal for stencil printing
86 – 87% Metal for dispensing

BALVER ZINN SOLDER PASTE PF32G SFMQ is available in SN96C (SnAg3,8Cu0,7) lead free alloys.
Type 4 powder from 20 – 38 micron is also available

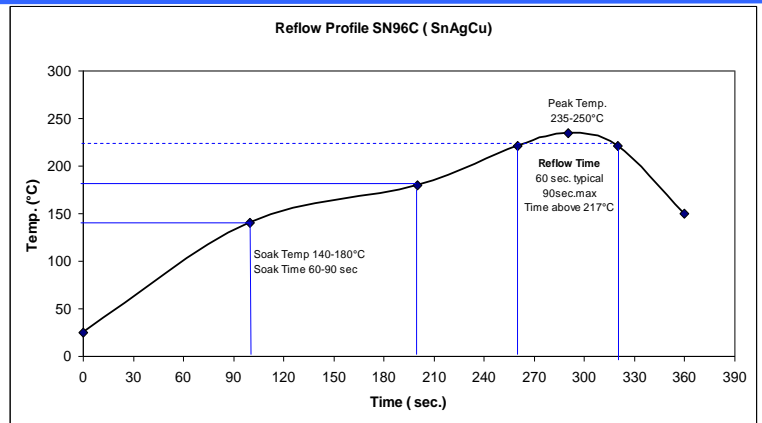
Electronic

BALVER ZINN®

Technical Data Sheet BALVER ZINN SOLDERPASTE PF32G SFMQ SN96C (SnAg3.8Cu0.7)

Recommended Reflow Profile:

The recommended reflow profile for **BALVER ZINN SOLDER PASTE PF32G SFMQ SN96C** offers a wide process window allowing adjustment to suit component board loadings. The illustrated profile is based on a full convection reflow system.



Printing Parameters:

DEK ProFlow and MPM Pumphead approved

Squeegee Blade	Stainless steel
Squeegee Speed	Capable of a max. printing speed of 150mm/sec
Stencil Material	Stainless steel
Temperature/Humidity	Optimal conditions are 21 – 25°C and 35 – 65% humidity.

Cleaning:

BALVER ZINN SOLDER PASTE PF32G SFMQ SN96C is a No-Clean formulation. The residues left on the board are non-conductive, non-corrosive and do not require removal in most applications. Although it is a No-Clean formulation, the residues can be easily removed with a variety of cleaning agents used in automated cleaning systems.

Delivery sizes:

Doses: 250g, 500g
Syringe/Cartridges: 5cc, 10cc, 30cc, 60cc, 120cc

Storage and shelf life:

It is recommended that **BALVER ZINN SOLDER PASTE PF32G SFMQ SN96C** is stored in clean dry conditions with a temperature of 5 – 10°C to maintain consistent reflow and print characteristics. **BALVER ZINN SOLDER PASTE PF32G SFMQ SN96C** should be equalized to room temperature prior to printing (minimum 8 hours). Do not use excessive heating. The time of storage in the original packaging at a temperature of 4 – 8°C amounts to 6 months in doses and 4 months in syringes or cartridges

Safety Advice

Before use please refer to the appropriate Safety Data Sheet.

Although the information in this data sheet is considered accurate, the measured values do not represent assured properties or delivery specifications. Because of the wide range of potential materials and applications, and with respect to possible protective rights and third parties, Balver Zinn Josef Jost GmbH & Co. KG **cannot** accept any liability.

OUR GLOBAL DISTRIBUTION NETWORK

Balver Zinn Josef Jost GmbH & Co. KG

Balve; Germany
☎: +49 2375 915 0
✉: cia@balverzinn.com
✓: www.balverzinn.com

Cobar Europe BV

Breda; The Netherlands
☎: +31 76 544 55 66
✉: info@cobar.com
✓: www.cobar.com

Cobar Solder Products Inc.

Little River; USA
☎: +1 (843) 734 1491
✉: info.usa@cobar.com
✓: www.cobar.com